



DRAM

COMPONENT

COMPONENT PART NUMBERING	「05
DDR / DDR2 SDRAM	「11
SDRAM	「13
GRAPHICS DDR SDRAM	「16
HANDY SDRAM	「19

:::::DRAM:::::

COMPONENT

DDR SDRAM PART NUMBERING

HY XX X XX XX X X X X X X X - XX X
 (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13) (14)

(1) HYNIX MEMORY

(2) PRODUCT FAMILY

5D : DDR SDRAM

(3) PROCESS & POWER SUPPLY

V : VDD=3.3V & VDDQ=2.5V
 U : VDD=2.5V & VDDQ=2.5V
 W : VDD=2.5V & VDDQ=1.8V
 S : VDD=1.8V & VDDQ=1.8V

(4) DENSITY & REFRESH

64 : 64M 4K Refresh
 66 : 64M 2K Refresh
 28 : 128M 4K Refresh
 56 : 256M 8K Refresh
 57 : 256M 4K Refresh
 12 : 512M 8K Refresh
 1G : 1G 8K Refresh

(5) ORGANIZATION

4 : x4
 8 : x8
 16 : x16
 32 : x32

(6) # of BANK

1 : 2Banks
 2 : 4Banks
 3 : 8Banks

(7) INTERFACE

1 : SSTL_3
 2 : SSTL_2
 3 : SSTL_18

(8) DIE GENERATION

BLANK : 1st Gen.
 A : 2nd Gen.
 B : 3rd Gen.
 C : 4th Gen

(14) TEMPERATURE

I : Industrial (-40 °C~85 °C)
 E : Extended (-25 °C~85 °C)

(13) SPEED

D5 : DDR500 3-4-4
 D43 : DDR400 3-3-3
 D4 : DDR400 3-4-4
 J : DDR333 2.5-3-3
 M : DDR266 2-2-2
 K : DDR266A 2-3-3
 H : DDR266A 2.5-3-3
 L : DDR200 2-2-2

(12) PACKAGE MATERIAL

BLANK : Normal
 P : Lead free(ROHS* Compliant)
 R : Lead & Halogen free
 (ROHS* Compliant)

(11) PACKAGE STACK

BLANK : Single Die
 S : Hynix Stack
 K : M & T Stack
 J : Others Stack
 M : Hynix DDP

(10) PACKAGE TYPE

T : TSOP
 Q : LQFP
 F : FBGA

(9) POWER CONSUMPTION

BLANK : Normal
 L : Low Power

♣ All DDR SDRAMs follow above Part Numbering System.
 * ROHS (Restriction of Hazardous Substances)

DDR2 SDRAM PART NUMBERING

HY XX X XX XX X X X X X - XX X
 (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13)

(1) HYNIX MEMORY

(2) PRODUCT FAMILY

5P : DDR2 SDRAM

(3) PROCESS & POWER SUPPLY

S : VDD=1.8V & VDDQ=1.8V

(4) DENSITY & REFRESH

28 : 128M 4K Refresh
 56 : 256M 8K Refresh
 12 : 512M 8K Refresh
 1G : 1G 8K Refresh
 2G : 2G 8K Refresh

(5) ORGANIZATION

4 : x4
 8 : x8
 16 : x16
 32 : x32

(6) # of BANK

1 : 2Banks
 2 : 4Banks
 3 : 8Banks

(7) INTERFACE

1 : SSTL_18
 2 : SSTL_2

(8) DIE GENERATION

BLANK : 1st Gen.
 A : 2nd Gen.
 B : 3rd Gen.
 C : 4th Gen.

(13) TEMPERATURE

I : Industrial (-40 °C~85 °C)
 E : Extended (-25 °C~85 °C)

(12) SPEED

S6 : DDR2-800 6-6-6
 S5 : DDR2-800 5-5-5
 Y6 : DDR2-667 6-6-6
 Y5 : DDR2-667 5-5-5
 Y4 : DDR2-667 4-4-4
 C5 : DDR2-533 5-5-5
 C4 : DDR2-533 4-4-4
 C3 : DDR2-533 3-3-3
 E4 : DDR2-400 4-4-4
 E3 : DDR2-400 3-3-3

(11) PACKAGE MATERIAL

BLANK : Normal
 P : Lead free(ROHS* Compliant)
 R : Lead & Halogen free
 (ROHS* Compliant)

(10) PACKAGE TYPE

F : FBGA Single Die
 S : FBGA Stack
 M : FBGA DDP(Dual Die Package)

(9) POWER CONSUMPTION

BLANK : Normal
 L : Low Power

♣ All DDR2 SDRAMs follow above Part Numbering System

* ROHS (Restriction of Hazardous Substances)

:::::DRAM::::: COMPONENT

SDRAM PART NUMBERING

HY XX X XX XX X X XX X X X - XX X
 (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13)

(1) HYNIX MEMORY

(2) PRODUCT FAMILY

57 : SDRAM

(3) PROCESS & POWER SUPPLY

V : VDD=3.3V & VDDQ=3.3V
 Y : VDD=3.0V & VDDQ=3.0V
 U : VDD=2.5V & VDDQ=2.5V
 W : VDD=2.5V & VDDQ=1.8V
 S : VDD=1.8V & VDDQ=1.8V

(4) DENSITY & REFRESH

16 : 16M
 32 : 32M
 64 : 64M
 28 : 128M
 2A : 128M With TCSR
 56 : 256M
 5A : 256M With TCSR
 12 : 512M

(5) ORGANIZATION

4 : x4
 8 : x8
 16 : x16
 32 : x32

(6) # of BANK

1 : 2Banks
 2 : 4Banks

(7) INTERFACE

0 : LVTTL
 1 : SSTL_3

(13) TEMPERATURE

BLANK : Commercial (0 ℃~70 ℃)
 I : Industrial (-40 ℃~85 ℃)
 E : Extended (-25 ℃~85 ℃)

(12) SPEED

5 : 200MHz
 55 : 183MHz
 6 : 166MHz
 7 : 143MHz
 K : PC133, CL2
 H : PC133, CL3
 8 : 125MHz
 P : PC100, CL2
 S : PC100, CL3
 10 : 100MHz

(11) PACKAGE MATERIAL

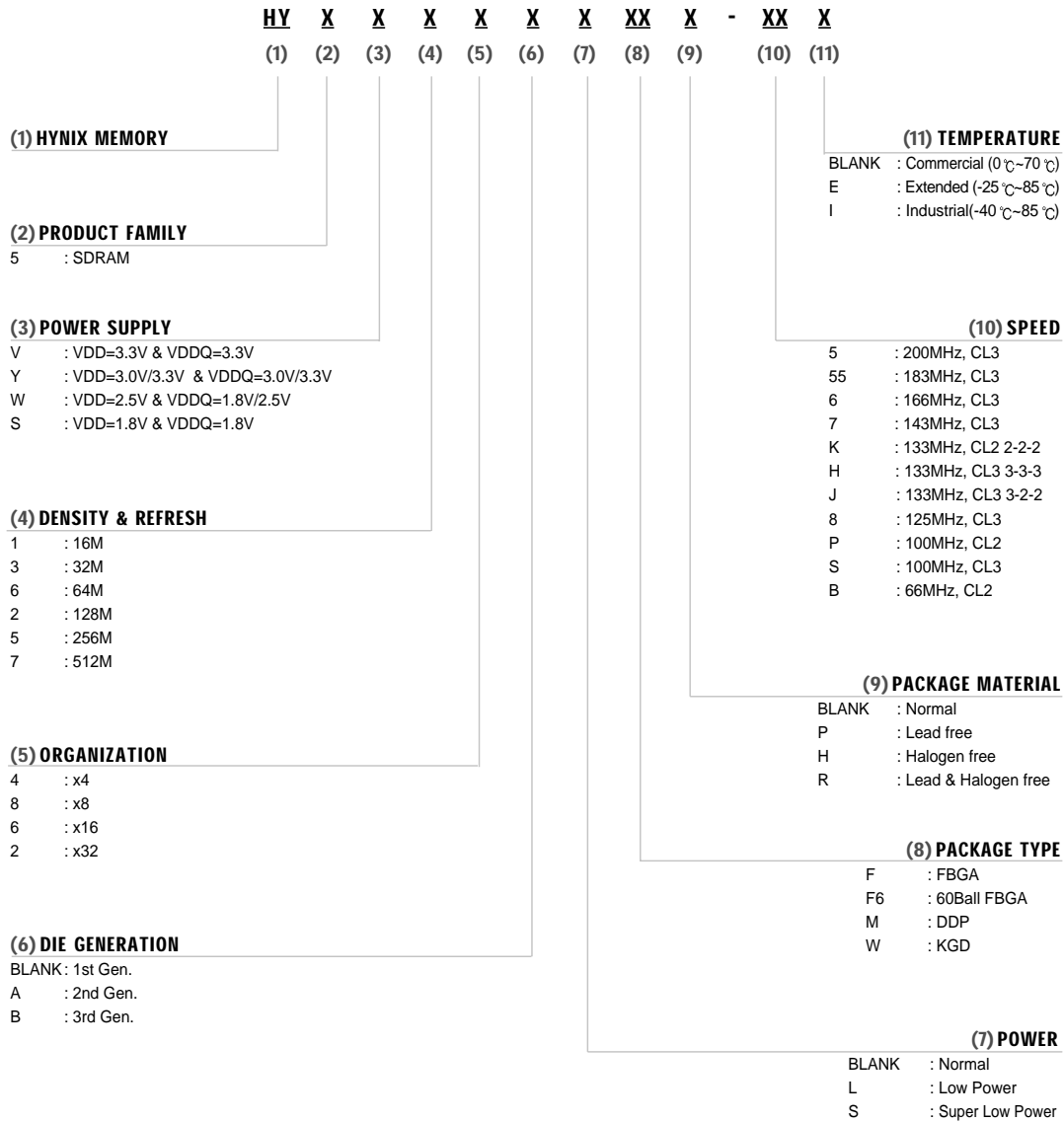
BLANK : Normal
 P : Lead free
 H : Halogen free
 R : Lead & Halogen free

(10) PACKAGE TYPE

T : TSOP
 S : Stack Package (Hynix)
 K : Stack Package (M & T)
 J : Stack Package (Others)
 W

31589368.5(: N PowerLVTTL)JTJ 0 -1.4286 L
 :uper(:ow PowerLVTTL)JTJ /F10 1 Tf 8.415 0 0 7.6.f 5.96t

SDRAM FBGA PART NUMBERING



♣ All SDRAM FBGA follow above Part Numbering System

:::::DRAM::::: COMPONENT

GRAPHICS MEMORY PART NUMBERING

HY XX X XX XX X X X X XX X - XX X
(1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13)

(1) HYNIX MEMORY

(2) PRODUCT FAMILY

5D : DDR SDRAM
 5Q : GDDR2 SDRAM
 5R : GDDR3 SDRAM

(3) PROCESS & POWER SUPPLY

V : VDD=3.3V & VDDQ=2.5V
 U : VDD=2.5V & VDDQ=2.5V
 W : VDD=2.5V & VDDQ=1.8V
 S : VDD=1.8V & VDDQ=1.8V

(4) DENSITY & REFRESH

32 : 32M 4K Refresh/32ms
 64 : 64M 4K Refresh/64ms
 66 : 64M 2K Refresh/16ms
 28 : 128M 4K Refresh/32ms
 56 : 256M 8K Refresh/64ms
 57 : 256M 4K Refresh/32ms
 58 : 256M 8K Refresh/32ms
 11 : 512M 4K Refresh/32ms
 12 : 512M 8K Refresh/32ms
 1G : 1G 8K Refresh/64ms
 2G : 2G 8K Refresh/64ms

(5) ORGANIZATION

16 : x16
 32 : x32

(6) # of BANK

1 : 2Banks
 2 : 4Banks
 3 : 8Banks

(7) INTERFACE

1 : SSTL_3
 2 : SSTL_2
 3 : SSTL_18
 4 : Reserved
 5 : POD_18

(8) DIE GENERATION

BLANK : 1st Gen.
 A : 2nd Gen.
 B : 3rd Gen.
 C : 4th Gen.
 D : 5th Gen.

(13) TEMPERATURE

I : Industrial (-40 °C~85 °C)
 E : Extended (-25 °C~85 °C)

(12) SPEED

12 : 800MHz
 14 : 700MHz
 16 : 600MHz
 18 : 550MHz
 2 : 500MHz
 22 : 450MHz
 25 : 400MHz
 26 : 375MHz
 28 : 350MHz
 3 : 333MHz
 33 : 300MHz
 36 : 275MHz
 4 : 250MHz
 43 : 233MHz
 45 : 222MHz
 5 : 200MHz
 55 : 183MHz
 6 : 166MHz

(11) PACKAGE MATERIAL

BLANK : Normal
 P : Lead free(ROHS* Compliant)
 R : Lead & Halogen free
 (ROHS* Compliant)

(10) PACKAGE TYPE

T : TSOP II
 Q : LQFP
 F : FBGA
 FM : MCP FBGA

(9) POWER CONSUMPTION

BLANK : Normal
 L : Low Power

HANDY DDR/SDR SDRAM PART NUMBERING

HY XX X X X X X X X X - X X
(1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12)

(1) HYNIX MEMORY

(2) PRODUCT FAMILY

5 : Handy SDR SDRAM
 5M : Handy DDR SDRAM

(3) POWER SUPPLY

Y : VDD=3.0V/3.3V & VDDQ=3.0V/3.3V
 W : VDD=2.5V & VDDQ=1.8V/2.5V
 S : VDD=1.8V & VDDQ=1.8V

(4) DENSITY

6 : 64M
 2 : 128M
 5 : 256M
 7 : 512M

(5) FUNCTION

A : Low Power Function (EMRS TCSR/PASR/DS/DPD)
 B : Low Power Function (AUTO TCSR/PASR/DS/DPD)

(6) ORGANIZATION

8 : x8
 6 : x16
 2 : x32

(7) DIE GENERATION

BLANK : 1st Gen.
 A : 2nd Gen.
 B : 3rd Gen.
 C : 4th Gen.
 D : 5th Gen.

(12) TEMPERATURE

BLANK : Commercial (0℃~70℃)
 F : PDA (-25℃~70℃)
 E : Extended (-25℃~85℃)
 I : Industrial(-40℃~85℃)

(11) SPEED

6 : 166MHz, CL3
 K : 133MHz, CL2 2-2-2 / DDR266
 H : 133MHz, CL3 3-3-3 / DDR266
 J : 133MHz, CL3 3-2-2
 P : 105MHz, CL2 / DDR200
 S : 105MHz, CL3 / DDR200
 B : 66MHz, CL2

(10) PACKAGE MATERIAL

BLANK : Normal
 P : Lead free
 H : Halogen free
 R : Lead & Halogen free

(9) PACKAGE TYPE

F : FBGA
 W : KGD
 D : Die Stack

(8) POWER

BLANK : Normal
 L : Low Power
 S : Super Low Power

♣ All HANDY SDRAM follow above Part Numbering System

DRAM

COMPONENT

DDR SDRAM COMPONENT

DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.			
1Gb	256MX4 (Stack)	DDR266A	HY5DU25422ATS-K HY5DU25422BTS-K	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2 4Bank,2.5V, CL2	Now 3Q04			
		DDR266B	HY5DU25422ATS-H HY5DU25422BTS-H	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now 3Q04			
		DDR400	HY5DU12422BF-D43 HY5DU12422CF-D43	FBGA(60ball) FBGA(60ball)	4Bank,2.6V, 3-3-3 4Bank,2.6V, 3-3-3	Now 4Q04			
		DDR333	HY5DU12422BF-J HY5DU12422CF-J	FBGA(60ball) FBGA(60ball)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now 4Q04			
512Mb	128MX4	DDR266A	HY5DU12422AT-K HY5DU12422BT-K	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2 4Bank,2.5V, CL2	Now Now			
		DDR266B	HY5DU12422CT-K HY5DU12422AT-H	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2 4Bank,2.5V, CL2.5	4Q04 Now			
		DDR200	HY5DU12422BT-H HY5DU12422CT-H	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now 4Q04			
			HY5DU12422AT-L HY5DU12422BT-L	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2 4Bank,2.5V, CL2	Now Now			
			HY5DU12422CT-L	TSOPII(66pin)	4Bank,2.5V, CL2	4Q04			
			64MX8	DDR400	HY5DU12822AT-D43 HY5DU12822BT-D43	TSOPII(66pin) TSOPII(66pin)	4Bank,2.6V, 3-3-3 4Bank,2.6V, 3-3-3	Now Now	
				DDR333	HY5DU12822BF-D43 HY5DU12822CT-D43	FBGA(60ball) TSOPII(66pin)	4Bank,2.6V, 3-3-3 4Bank,2.6V, 3-3-3	Now 4Q04	
					HY5DU12822CF-D43	FBGA(60ball)	4Bank,2.6V, 3-3-3	4Q04	
		HY5DU12822AT-J HY5DU12822BT-J			TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now Now		
		DDR266B		HY5DU12822BF-J HY5DU12822CT-J	FBGA(60ball) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now 4Q04		
				HY5DU12822CF-J	FBGA(60ball)	4Bank,2.5V, CL2.5	4Q04		
			HY5DU12822AT-H HY5DU12822BT-H	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now Now			
	HY5DU12822BF-H HY5DU12822CT-H		FBGA(60ball) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now 4Q04				
	HY5DU12822CF-H		FBGA(60ball)	4Bank,2.5V, CL2.5	4Q04				
	32MX16		DDR400	HY5DU121622AT-D43 HY5DU121622BT-D43	TSOPII(66pin) TSOPII(66pin)	4Bank,2.6V, 3-3-3 4Bank,2.6V, 3-3-3	Now Now		
		HY5DU121622CT-D43		TSOPII(66pin)	4Bank,2.6V, 3-3-3	4Q04			
		DDR333		HY5DU121622AT-J HY5DU121622BT-J	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now Now		
				HY5DU121622CT-J	TSOPII(66pin)	4Bank,2.5V, CL2.5	4Q04		
		DDR266B	HY5DU121622AT-H HY5DU121622BT-H	TSOPII(66pin) TSOPII(66pin)	4Bank,2.5V, CL2.5 4Bank,2.5V, CL2.5	Now Now			
			HY5DU121622CT-H	TSOPII(66pin)	4Bank,2.5V, CL2.5	4Q04			
			256Mb	64Mx4	DDR400	HY5DU56422BF-D43 HY5DU56422DF-D43	FBGA(60ball) FBGA(60ball)	4Bank, 2.6V, 3-3-3 4Bank, 2.6V, 3-3-3	Now Now
					DDR333	HY5DU56422BF-J HY5DU56422DF-J	FBGA(60ball) FBGA(60ball)	4Bank, 2.5V, CL2.5 4Bank, 2.5V, CL2.5	Now Now
		DDR266A			HY5DU56422BT-K HY5DU56422DT-K	TSOPII(66pin) TSOPII(66pin)	4Bank, 2.5V, CL2 4Bank, 2.5V, CL2	Now Now	
		DDR266B			HY5DU56422BT-H HY5DU56422DT-H	TSOPII(66pin) TSOPII(66pin)	4Bank, 2.5V, CL2.5 4Bank, 2.5V, CL2.5	Now Now	
DDR200			HY5DU56422BT-L HY5DU56422DT-L		TSOPII(66pin) TSOPII(66pin)	4Bank, 2.5V, CL2 4Bank, 2.5V, CL2	Now Now		
32Mx8		DDR500	HY5DU56822DT-D5		TSOPII(66pin)	4Bank, 2.7V, 3-4-4	Now		
	DDR400	HY5DU56822BT-D43 HY5DU56822DT-D43	TSOPII(66pin) TSOPII(66pin)		4Bank, 2.6V, 3-3-3 4Bank, 2.6V, 3-3-3	Now Now			



DRAM

COMPONENT

DDR SDRAM COMPONENT

DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.
256Mb	32Mx8	DDR333	HY5DU56822BT-J	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
			HY5DU56822DT-J	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
		DDR266A	HY5DU56822BT-K	TSOPII(66pin)	4Bank, 2.5V, CL2	Now
			HY5DU56822DT-K	TSOPII(66pin)	4Bank, 2.5V, CL2	Now
		DDR266B	HY5DU56822BT-H	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
			HY5DU56822DT-H	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
16Mx16	DDR400	HY5DU561622D(L)T-D43	TSOPII(66pin)	4Bank, 2.6V, 3-3-3	Now	
		HY5DU561622D(L)T-J	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now	
		HY5DU561622D(L)T-H	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now	
		TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now		
128Mb	16Mx8	DDR333	HY5DU28822ET-J	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
		DDR266A	HY5DU28822ET-K	TSOPII(66pin)	4Bank, 2.5V, CL2	Now
		DDR266B	HY5DU28822ET-H	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
	8Mx16	DDR333	HY5DU281622ET-J	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
		DDR266B	HY5DU281622ET-H	TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now
		TSOPII(66pin)	4Bank, 2.5V, CL2.5	Now		

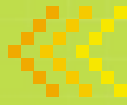
DDR2 SDRAM COMPONENT

DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.	
2Gb*	512Mx4	DDR2 533	HY5PS2G431M-C4	FBGA(71ball)	8Bank, 1.8V, CL4,4-4-4	3Q04	
		DDR2 400	HY5PS2G431M-E3	FBGA(71ball)	8Bank, 1.8V, CL3,3-3-3	3Q04	
	256Mx8	DDR2 533	HY5PS2G831M-C4	FBGA(71ball)	8Bank, 1.8V, CL4,4-4-4	3Q04	
		DDR2 400	HY5PS2G831M-E3	FBGA(71ball)	8Bank, 1.8V, CL3,3-3-3	3Q04	
1Gb	256Mx4	DDR2 533	HY5PS1G431F-C4	FBGA(68ball)	8Bank, 1.8V, CL4,4-4-4	3Q04	
		DDR2 400	HY5PS1G431F-E3	FBGA(68ball)	8Bank, 1.8V, CL3,3-3-3	3Q04	
	128Mx8	DDR2 667	HY5PS1G831F-Y5	FBGA(68ball)	8Bank, 1.8V, CL5,5-5-5	3Q04	
		DDR2 533	HY5PS1G831F-C4	FBGA(68ball)	8Bank, 1.8V, CL4,4-4-4	3Q04	
	DDR2 400	HY5PS1G831F-E3	FBGA(68ball)	8Bank, 1.8V, CL3,3-3-3	3Q04		
		FBGA(68ball)	8Bank, 1.8V, CL3,3-3-3	3Q04			
1Gb*	256Mx4	DDR2 533	HY5PS1G421M-C4	FBGA(63ball)	4Bank, 1.8V, CL4,4-4-4	Now	
		DDR2 400	HY5PS1G421M-E3	FBGA(63ball)	4Bank, 1.8V, CL3,3-3-3	Now	
	128Mx8	DDR2 533	HY5PS1G821M-C4	FBGA(63ball)	4Bank, 1.8V, CL4,4-4-4	Now	
		DDR2 400	HY5PS1G821M-E3	FBGA(63ball)	4Bank, 1.8V, CL3,3-3-3	Now	
	512Mb	128Mx4	DDR2 533	HY5PS12421F-C4	FBGA(60ball)	4Bank, 1.8V, CL4,4-4-4	Now
			DDR2 400	HY5PS12421F-E3	FBGA(60ball)	4Bank, 1.8V, CL3,3-3-3	Now
64Mx8		DDR2 667	HY5PS12821F-Y5	FBGA(60ball)	4Bank, 1.8V, CL5,5-5-5	3Q04	
		DDR2 533	HY5PS12821F-C4	FBGA(60ball)	4Bank, 1.8V, CL4,4-4-4	Now	
		DDR2 400	HY5PS12821F-E3	FBGA(60ball)	4Bank, 1.8V, CL3,3-3-3	Now	
32Mx16		DDR2 667	HY5PS121621F-Y5	FBGA(84ball)	4Bank, 1.8V, CL5,5-5-5	3Q04	
	HY5PS121621AF-Y5		FBGA(84ball)	4Bank, 1.8V, CL5,5-5-5	3Q04		
	DDR2 533	HY5PS121621F-C4	FBGA(84ball)	4Bank, 1.8V, CL4,4-4-4	Now		
		HY5PS121621AF-C4	FBGA(84ball)	4Bank, 1.8V, CL4,4-4-4	3Q04		
		HY5PS121621F-E3	FBGA(84ball)	4Bank, 1.8V, CL3,3-3-3	Now		
FBGA(84ball)	4Bank, 1.8V, CL3,3-3-3	3Q04					
256Mb	64Mx4	DDR2 533	HY5PS56421F-C4	FBGA(60ball)	4Bank, 1.8V, CL4,4-4-4	Now	
		DDR2 400	HY5PS56421F-E3	FBGA(60ball)	4Bank, 1.8V, CL3,3-3-3	Now	
	32Mx8	DDR2 667	HY5PS56821F-Y5	FBGA(60ball)	4Bank, 1.8V, CL5,5-5-5	Now	
		DDR2 533	HY5PS56821F-C4	FBGA(60ball)	4Bank, 1.8V, CL4,4-4-4	Now	
		DDR2 400	HY5PS56821F-E3	FBGA(60ball)	4Bank, 1.8V, CL3,3-3-3	Now	
	16Mx16	DDR2 667	HY5PS561621F-Y5	FBGA(84ball)	4Bank, 1.8V, CL5,5-5-5	3Q04	
DDR2 533		HY5PS561621F-C4	FBGA(84ball)	4Bank, 1.8V, CL4,4-4-4	Now		
DDR2 400		HY5PS561621F-E3	FBGA(84ball)	4Bank, 1.8V, CL3,3-3-3	Now		

* DDP type Stack

DRAM

COMPONENT



SDRAM COMPONENT

DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.
512Mb (Stack)	16M x 32	PC133	HY5V72D(L)M-H	FBGA(90ball)	4Bank,3.3V, DDP	3Q04
		PC100	HY5V72D(L)M-P	FBGA(90ball)	4Bank,3.3V, DDP	3Q04
256Mb	64M x 4	PC133	HY57V56420C(L)T-H	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V56420C(L)T-P	TSOPII(54pin)	4Bank, 3.3V	Now
		PC133	HY57V56420C(L)T-S	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V56820C(L)T-H	TSOPII(54pin)	4Bank, 3.3V	Now
	32M x 8	PC100	HY57V56820C(L)T-P	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V56820C(L)T-S	TSOPII(54pin)	4Bank, 3.3V	Now
	16M x 16	PC133	HY57V561620C(L)T-H	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V561620C(L)T-P	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V561620C(L)T-S	TSOPII(54pin)	4Bank, 3.3V	Now
		166MHz (6ns)	HY57V561620D(L)T-P	TSOPII(54pin)	4Bank, 3.3V	Now
		143MHz (7ns)	HY57V561620C(L)T-6	TSOPII(54pin)	4Bank, 3.3V	Now
		PC133	HY57V561620C(L)T-7	TSOPII(54pin)	4Bank, 3.3V	Now
	8M x 32	PC133	HY5V56D(S/L)F-H	FBGA(54ball)	4Bank, 3.3V	Now
		PC133	HY5V52C(L)F-H	FBGA(90ball)	4Bank, 3.3V, DDP	Now
		PC100	HY5V52C(L)F-P	FBGA(90ball)	4Bank, 3.3V, DDP	Now
		PC100	HY5V52C(L)F-S	FBGA(90ball)	4Bank, 3.3V, DDP	Now
		166MHz (6ns)	HY5V52C(L)F-6	FBGA(90ball)	4Bank, 3.3V,DDP	Now
		166MHz (6ns)	HY5V52C(L)F-6	FBGA(90ball)	4Bank, 3.3V	3Q04
		166MHz (6ns)	HY5V52C(L)F-6	FBGA(90ball)	4Bank, 3.3V	3Q04
		166MHz (6ns)	HY5V52C(L)F-6	FBGA(90ball)	4Bank, 3.3V	3Q04
128Mb	32M x 4	PC133	HY57V28420HC(L)T-H	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V28420HC(L)T-P	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V28420HC(L)T-S	TSOPII(54pin)	4Bank, 3.3V	Now
		166MHz (6ns)	HY57V28420HC(L)T-6	TSOPII(54pin)	4Bank, 3.3V	Now
	16M x 8	PC133	HY57V28820HC(L)T-H	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V28820HCT-P	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V28820HCT-K	TSOPII(54pin)	4Bank, 3.3V	Now
		PC100	HY57V28820HCT-S	TSOPII(54pin)	4Bank, 3.3V	Now
		166MHz (6ns)	HY57V28820HCT-6	TSOPII(54pin)	4Bank, 3.3V	Now
		125MHz (8ns)	HY57V28820HCT-8	TSOPII(54pin)	4Bank, 3.3V	Now
		PC133	HY5V28C(L/S)F-H	FBGA(54ball)	4Bank, 3.3V	EOL
		PC100	HY5V28C(L/S)F-P	FBGA(54ball)	4Bank, 3.3V	EOL
	8M x 16	PC133	HY5V28C(L/S)F-S	FBGA(54ball)	4Bank, 3.3V	EOL
		PC100	HY5V28C(L/S)F-6	FBGA(54ball)	4Bank, 3.3V	EOL
		PC100	HY5V28C(L/S)F-8	FBGA(54ball)	4Bank, 3.3V	EOL
		200MHz (5ns)	HY57V281620HC(L/S)T-H	TSOPII(54pin)	4Bank, 3.3V	Now
		183MHz (5.5ns)	HY57V281620HC(L/S)T-P	TSOPII(54pin)	4Bank, 3.3V	Now
		166MHz (6ns)	HY57V281620HC(L/S)T-S	TSOPII(54pin)	4Bank, 3.3V	Now
		143MHz (7ns)	HY57V281620HC(L)T-5	TSOPII(54pin)	4Bank, 3.3V	Now
		143MHz (7ns)	HY57V281620HC(L)T-55	TSOPII(54pin)	4Bank, 3.3V	Now
125MHz (8ns)		HY57V281620HC(L)T-6	TSOPII(54pin)	4Bank, 3.3V	Now	
125MHz (8ns)		HY57V281620HC(L)T-7	TSOPII(54pin)	4Bank, 3.3V	Now	
125MHz (8ns)		HY57V281620HC(L)T-8	TSOPII(54pin)	4Bank, 3.3V	Now	
PC133		HY5V26C(L/S)F-H	FBGA(54ball)	4Bank, 3.3V	EOL	
4M x 32	PC100	HY5V26D(L/S)F-H	FBGA(54ball)	4Bank, 3.3V	Now	
	PC100	HY5V26C(L/S)F-P	FBGA(54ball)	4Bank, 3.3V	EOL	
	PC100	HY5V26D(L/S)F-P	FBGA(54ball)	4Bank, 3.3V	Now	
	PC100	HY5V26C(L/S)F-S	FBGA(54ball)	4Bank, 3.3V	EOL	
	166MHz (6ns)	HY5V26C(L/S)F-6	FBGA(54ball)	4Bank, 3.3V	EOL	
	125MHz (8ns)	HY5V26C(L/S)F-8	FBGA(54ball)	4Bank, 3.3V	EOL	
	PC133	HY5V283220T-H	TSOPII(86pin)	4Bank, 3.3V	Now	

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DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.
64Mb	4M x 16	166MHz (6ns)	HY57V641620HG(L)T-6	TSOPII(54pin)	4Bank, 3.3V	Now
			HY57V641620E(L)T-6	TSOPII(54pin)	4Bank, 3.3V	4Q04
		143MHz (7ns)	HY57V641620HG(L)T-7	TSOPII(54pin)	4Bank, 3.3V	Now
			HY57V641620E(L)T-7	TSOPII(54pin)	4Bank, 3.3V	4Q04
		PC133	HY5V66DF6-K	FBGA(60ball)	4Bank, 3.3V	EOL
			HY5V66DF6-H	FBGA(60ball)	4Bank, 3.3V	Now
			HY5V66EF-K	FBGA(60ball)	4Bank, 3.3V	Now
			HY5V66EF-H	FBGA(54ball)	4Bank, 3.3V	4Q04
			HY5V66GF-H	FBGA(54ball)	4Bank, 3.3V	4Q04
			HY5V66GF-P	FBGA(60ball)	4Bank, 3.3V	EOL
		PC100	HY5V66DF6-P	FBGA(60ball)	4Bank, 3.3V	Now
			HY5V66DF6-S	FBGA(60ball)	4Bank, 3.3V	Now
			HY5V66EF-P	FBGA(54ball)	4Bank, 3.3V	4Q04
			HY5V66EF-S	FBGA(54ball)	4Bank, 3.3V	4Q04
	200MHz (5ns)		HY5V66EF-5	FBGA(54ball)	4Bank, 3.3V	4Q04
	183MHz (5.5ns)		HY5V66EF-55	FBGA(54ball)	4Bank, 3.3V	4Q04
	2M x 32	166MHz (6ns)	HY5V66EF-6	FBGA(54ball)	4Bank, 3.3V	4Q04
			143MHz (7ns)	HY5V66EF-7	FBGA(54ball)	4Bank, 3.3V
		200MHz (5ns)	HY57V643220CT-5	TSOPII(86pin)	4Bank,3.3V	EOL
			HY57V643220DT-5	TSOPII(86pin)	4Bank,3.3V	Now
		183MHz (5.5ns)	HY57V643220CT-55	TSOPII(86pin)	4Bank,3.3V	EOL
			HY57V643220DT-55	TSOPII(86pin)	4Bank,3.3V	Now
		166MHz (6ns)	HY57V643220CT-6	TSOPII(86pin)	4Bank,3.3V	EOL
			HY57V643220DT-6	TSOPII(86pin)	4Bank,3.3V	Now
143MHz (7ns)		HY57V643220CT-7	TSOPII(86pin)	4Bank,3.3V	EOL	
		HY57V643220DT-7	TSOPII(86pin)	4Bank,3.3V	Now	
125MHz (8ns)	HY57V643220CT-8	TSOPII(86pin)	4Bank,3.3V	EOL		
	HY57V643220DT-8	TSOPII(86pin)	4Bank,3.3V	Now		
16Mb	1M x 16	200MHz (5ns)	HY57V161610DTC-5	TSOPII(50pin)	2Bank, 3.3V	EOL
			HY57V161610ET-5	TSOPII(50pin)	2Bank, 3.3V	Now
		183MHz (5.5ns)	HY57V161610DTC-55	TSOPII(50pin)	2Bank, 3.3V	EOL
			HY57V161610ET-55	TSOPII(50pin)	2Bank, 3.3V	Now
		166MHz (6ns)	HY57V161610DTC-6	TSOPII(50pin)	2Bank, 3.3V	EOL
			HY57V161610ET-6	TSOPII(50pin)	2Bank, 3.3V	Now
		143MHz (7ns)	HY57V161610DTC-7	TSOPII(50pin)	2Bank, 3.3V	EOL
			HY57V161610ET-7	TSOPII(50pin)	2Bank, 3.3V	Now
		133MHz (7.5ns)	GM72V161621ET-7	TSOPII(50pin)	2Bank, 3.3V	EOL
			HY57V161610EW-75	KGD	2Bank, 3.3V	Now
		125MHz (8ns)	HY5V16EF6-75	FBGA(60ball)	2Bank, 3.3V	Now
			HY57V161610DTC-8	TSOPII(50pin)	2Bank, 3.3V	EOL
		100MHz (10ns)	HY57V161610ET-8	TSOPII(50pin)	2Bank, 3.3V	Now
			GM72V161621ET-8	TSOPII(50pin)	2Bank, 3.3V	EOL
			HY57V161610DTC-10	TSOPII(50pin)	2Bank, 3.3V	Now
			HY5V16EF6-10	FBGA(60ball)	2Bank, 3.3V	Now

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DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.		
512Mb	32Mx16	200MHz (5ns)	HY5DU121622AT-5	TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
			HY5DU121622BT-5	TSOPII(66pin)	4Bank, 2.5V/2.5V	4Q04		
		166MHz (6ns)	HY5DU121622AT-6	TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
			HY5DU121622BT-6	TSOPII(66pin)	4Bank, 2.5V/2.5V	4Q04		
	16Mx32	450MHz (2.2ns)	HY5DU113222FM-22	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04		
			HY5DW113222FM-22	FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04		
		400MHz (2.5ns)	HY5DU113222FM-25	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04		
			HY5DW113222FM-25	FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04		
		350MHz (2.8ns)	HY5DU113222FM-28	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04		
			HY5DW113222FM-28	FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04		
		300MHz (3.3ns)	HY5DS113222FM-28	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04		
			HY5DU113222FM-33	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04		
		275MHz (3.6ns)	HY5DW113222FM-33	FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04		
			HY5DS113222FM-33	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04		
		250MHz (4ns)	HY5DU113222FM-36	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04		
			HY5DW113222FM-36	FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04		
			HY5DS113222FM-36	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04		
			HY5DU113222FM-4	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04		
		256Mb	16Mx16	400MHz (2.5ns)	HY5DU561622CT-25	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now
					HY5DU561622CT-28	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now
350MHz (2.8ns)	HY5DU561622CT-33			TSOPII(66pin)	4Bank, 2.6V/2.6V	Now		
	HY5DU561622CT-36			TSOPII(66pin)	4Bank, 2.6V/2.6V	Now		
275MHz (3.6ns)	HY5DU561622DT-36			TSOPII(66pin)	4Bank, 2.6V/2.6V	Now		
	HY5DU561622CT-4			TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
250MHz (4ns)	HY5DU561622DT-4			TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
	HY5DU561622CT-5			TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
200MHz (5ns)	HY5DU561622DT-5			TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
	HY5DU561622CT-6			TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
166MHz (6ns)	HY5DU561622DT-6			TSOPII(66pin)	4Bank, 2.5V/2.5V	Now		
	450MHz (2.2ns)			HY5DU573222F-22	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04	
			HY5DW573222F-22	FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04		
	400MHz (2.5ns)		HY5DU573222AFM-25	FBGA(144ball)	4Bank, 2.8V/2.8V	Now		
HY5DU573222F-25			FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04			
350MHz (2.8ns)	HY5DW573222F-25		FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04			
	HY5DU573222AFM-28	FBGA(144ball)	4Bank, 2.8V/2.8V	Now				
300MHz (3.3ns)	HY5DU573222F-28	FBGA(144ball)	4Bank, 2.5V/2.5V	3Q04				
	HY5DW573222F-28	FBGA(144ball)	4Bank, 2.5V/1.8V	3Q04				
275MHz (3.6ns)	HY5DS573222F-28	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04				
	HY5DU573222AFM-33	FBGA(144ball)	4Bank, 2.5V/2.5V	Now				
128Mb	8Mx16	400MHz(2.5ns)	HY5DU281622ET-25	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now		
			HY5DU281622ET-26	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now		
		375MHz(2.6ns)	HY5DU281622ET-28	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now		
			HY5DU281622ET-28	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now		

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DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.	
128Mb	8M x 16	333MHz(3ns)	HY5DU281622ET-3	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now	
		300MHz(3.3ns)	HY5DU281622ET-33	TSOPII(66pin)	4Bank, 2.8V/2.8V	Now	
		275MHz(3.6ns)	HY5DU281622ET-36	TSOPII(66pin)	4Bank, 2.5V/2.5V	Now	
			HY5DV281622DT-36	TSOPII(66pin)	4Bank, 3.3V/2.5V	EOL	
		250MHz(4ns)	HY5DU281622ET-4	TSOPII(66pin)	4Bank, 2.5V/2.5V	Now	
			HY5DV281622DT-4	TSOPII(66pin)	4Bank, 3.3V/2.5V	EOL	
		200MHz(5ns)	HY5DU281622ET-5	TSOPII(66pin)	4Bank, 2.5V/2.5V	Now	
			HY5DV281622DT-5	TSOPII(66pin)	4Bank, 3.3V/2.5V	EOL	
		166MHz(6ns)	HY5DU281622ET-6	TSOPII(66pin)	4Bank, 2.5V/2.5V	Now	
			HY5DV281622DT-6	TSOPII(66pin)	4Bank, 2.5V/2.5V	EOL	
		4Mx32	500MHz(2ns)	HY5DU283222AF-2	FBGA(144ball)	4Bank, 2.8V/2.8V	Now
			450MHz(2.2ns)	HY5DU283222AF-22	FBGA(144ball)	4Bank, 2.8V/2.8V	Now
				HY5DU283222BF-22	FBGA(144ball)	4Bank, 2.5V/2.5V	4Q04
				HY5DW283222AF-22	FBGA(144ball)	4Bank, 2.8V/1.8V	Now
			HY5DW283222BF-22	FBGA(144ball)	4Bank, 2.5V/1.8V	4Q04	
	400MHz(2.5ns)		HY5DU283222AF-25	FBGA(144ball)	4Bank, 2.8V/2.8V	Now	
			HY5DU283222BF-25	FBGA(144ball)	4Bank, 2.5V/2.5V	4Q04	
			HY5DW283222AF-25	FBGA(144ball)	4Bank, 2.5V/1.8V	Now	
			HY5DW283222BF-25	FBGA(144ball)	4Bank, 2.5V/1.8V	4Q04	
	350MHz(2.8ns)		HY5DU283222AF-28	FBGA(144ball)	4Bank, 2.8V/2.8V	Now	
			HY5DU283222BF-28	FBGA(144ball)	4Bank, 2.5V/2.5V	4Q04	
			HY5DW283222AF-28	FBGA(144ball)	4Bank, 2.5V/1.8V	Now	
			HY5DW283222BF-28	FBGA(144ball)	4Bank, 2.5V/1.8V	4Q04	
	300MHz(3.3ns)		HY5DS283222BF-28	FBGA(144ball)	4Bank, 1.8V/1.8V	4Q04	
			HY5DU283222AF-33	FBGA(144ball)	4Bank, 2.5V/2.5V	Now	
			HY5DU283222AQ-33	LQFP(100pin)	4Bank, 2.5V/2.5V	Now	
		HY5DU283222BF-33	FBGA(144ball)	4Bank, 2.5V/2.5V	4Q04		
		HY5DW283222AF-33	FBGA(144ball)	4Bank, 2.5V/1.8V	Now		
		HY5DW283222BF-33	FBGA(144ball)	4Bank, 2.5V/1.8V	4Q04		
		HY5DS283222BF-33	FBGA(144ball)	4Bank, 1.8V/1.8V	4Q04		
275MHz(3.6ns)	HY5DU283222AF-36	FBGA(144ball)	4Bank, 2.5V/2.5V	Now			
	HY5DU283222AQ-36	LQFP(100pin)	4Bank, 2.5V/2.5V	Now			
	HY5DU283222BF-36	FBGA(144ball)	4Bank, 2.5V/2.5V	4Q04			
	HY5DW283222AF-36	FBGA(144ball)	4Bank, 2.5V/1.8V	Now			
	HY5DW283222BF-36	FBGA(144ball)	4Bank, 2.5V/1.8V	4Q04			
	HY5DS283222BF-36	FBGA(144ball)	4Bank, 1.8V/1.8V	4Q04			
250MHz(4ns)	HY5DU283222AQ-4	LQFP(100pin)	4Bank, 2.5V/2.5V	Now			
	HY5DU283222BF-4	FBGA(144ball)	4Bank, 2.5V/2.5V	4Q04			
	HY5DW283222AF-4	FBGA(144ball)	4Bank, 2.5V/1.8V	4Q04			
	HY5DW283222BF-4	FBGA(144ball)	4Bank, 2.5V/1.8V	4Q04			
	HY5DS283222BF-4	FBGA(144ball)	4Bank, 1.8V/1.8V	4Q04			
200MHz(5ns)	HY5DU283222AQ-5	LQFP(100pin)	4Bank, 2.5V/2.5V	Now			

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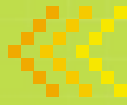
DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.
512Mb	32Mx16	400MHz(2.5ns)	HY5PS121621F-25	FBGA(86ball)	4Bank, 2.1V/2.1V	Now
		350MHz(2.8ns)	HY5PS121621F-28	FBGA(86ball)	4Bank, 2.0V/2.0V	Now
		300MHz(3.3ns)	HY5PS121621F-33	FBGA(86ball)	4Bank, 2.0V/2.0V	Now
256Mb	16Mx16	400MHz(2.5ns)	HY5PS561621F-25	FBGA(86ball)	4Bank, 2.1V/2.1V	Now
		350MHz(2.8ns)	HY5PS561621F-28	FBGA(86ball)	4Bank, 2.0V/2.0V	Now
		300MHz(3.3ns)	HY5PS561621F-33	FBGA(86ball)	4Bank, 2.0V/2.0V	Now
		275MHz(3.6ns)	HY5PS561621F-36	FBGA(86ball)	4Bank, 2.0V/2.0V	Now

GRAPHICS DDR3 SDRAM

DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.
512Mb	16Mx32	1GHz(1ns)	HY5RS113225F-1	FBGA(136ball)	8Bank, 1.8V/1.8V	4Q04
		900MHz(1.1ns)	HY5RS113225F-11	FBGA(136ball)	8Bank, 1.8V/1.8V	4Q04
		800MHz(1.2ns)	HY5RS113225F-12	FBGA(136ball)	8Bank, 1.8V/1.8V	4Q04
		700MHz(1.4ns)	HY5RS113225F-14	FBGA(136ball)	8Bank, 1.8V/1.8V	4Q04
		600MHz(1.6ns)	HY5RS113225F-16	FBGA(136ball)	8Bank, 1.8V/1.8V	4Q04
256Mb	8Mx32	800MHz(1.2ns)	HY5RS573225F-12	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04
		750MHz(1.3ns)	HY5RS573225F-13	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04
		700MHz(1.4ns)	HY5RS573225F-14	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04
		650MHz(1.5ns)	HY5RS573225F-15	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04
		600MHz(1.6ns)	HY5RS573225F-16	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04
		550MHz(1.8ns)	HY5RS573225F-18	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04
		500MHz(2.0ns)	HY5RS573225F-2	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04
		450MHz(2.2ns)	HY5RS573225F-22	FBGA(144ball)	4Bank, 1.8V/1.8V	3Q04

DRAM

COMPONENT



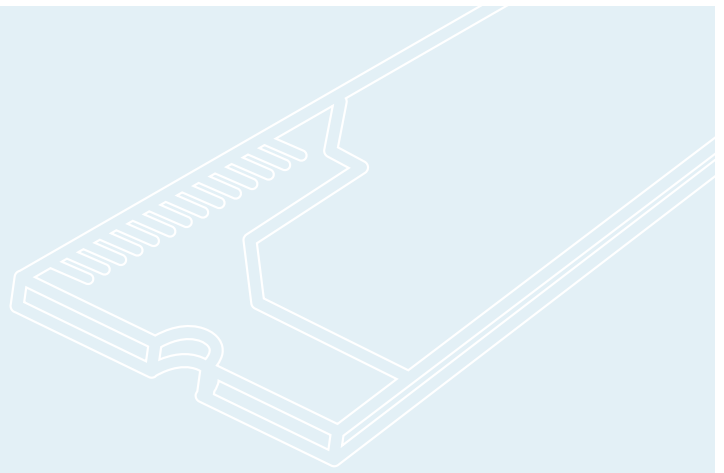
HANDY SDRAM

DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.	
512M	32Mx16	166MHz (6ns)	HY5S7B6LF(P)-6E	FBGA(54ball)	4Bank, 1.8V/1.8V	1Q05	
		133MHz (7.5ns)	HY5S7B6LF(P)-HE	FBGA(54ball)	4Bank, 1.8V/1.8V	1Q05	
		105MHz (9.5ns)	HY5S7B6LF(P)-PE	FBGA(54ball)	4Bank, 1.8V/1.8V	1Q05	
	16M x 32	133MHz (7.5ns)	HY5W7A2D(L)F(P)-HF	FBGA(90ball)	4Bank, 2.5V/2.5V	3Q04	
		105MHz (9.5ns)	HY5Y7A2D(L)F(P)-HF	FBGA(90ball)	4Bank, 3.0V/3.0V	3Q04	
			HY5W7A2D(L)F(P)-PF	FBGA(90ball)	4Bank, 2.5V/2.5V	3Q04	
256Mb	16M x 16	133MHz (7.5ns)	HY5Y5A6D(L/S)F(P)-HF	FBGA(54ball)	4Bank, 3.0/3.0V	Now	
			HY5W5A6D(L/S)F(P)-HF	FBGA(54ball)	4Bank, 2.5V/2.5V	Now	
			HY5S5B6ELF(P)-HE	FBGA(54ball)	4Bank, 1.8/1.8V	4Q04	
		105MHz (9.5ns)	HY5Y5A6D(L/S)F(P)-PF	FBGA(54ball)	4Bank, 3.0V/3.0V	Now	
			HY5W5A6D(L/S)F(P)-PF	FBGA(54ball)	4Bank, 2.5V/2.5V	Now	
			HY5S5A6D(L/S)F(P)-SE	FBGA(54ball)	4Bank, 1.8V/1.8V	Now	
		8M x 32	133MHz (7.5ns)	HY5S5B6ELF(P)-PE	FBGA(54ball)	4Bank, 1.8V/1.8V	4Q04
				HY5Y5B2LF(P)-HE	FBGA(90ball)	4Bank, 3.0/3.0V	4Q04
				HY5W5B2LF(P)-HE	FBGA(90ball)	4Bank, 2.5V/2.5V	4Q04
	128Mb	8M x 16	133MHz (7.5ns)	HY5Y5B2LF(P)-PE	FBGA(90ball)	4Bank, 3.0V/3.0V	4Q04
				HY5W5B2LF(P)-PE	FBGA(90ball)	4Bank, 2.5V/2.5V	4Q04
				HY5S5B2LF(P)-SE	FBGA(90ball)	4Bank, 1.8V/1.8V	4Q04
			105MHz (9.5ns)	HY5W2B6D(L/S)F(P)-HE	FBGA(54ball)	4Bank, 2.5V/2.5V	Now
				HY5Y2B6D(L/S)F(P)-HE	FBGA(54ball)	4Bank, 3.0V/3.0V	Now
				HY5W2B6D(L/S)F(P)-PE	FBGA(54ball)	4Bank, 2.5V/2.5V	Now
64Mb	4M x 16	133MHz (7.5ns)	HY5Y2B6D(L/S)F(P)-PE	FBGA(54ball)	4Bank, 3.0V/3.0V	Now	
			HY5S2B6D(L/S)F(P)-SE	FBGA(54ball)	4Bank, 1.8V/1.8V	Now	
			HY5W2B2A(L/S)F(P)-HE	FBGA(90ball)	4Bank, 2.5V/2.5V	3Q04	
		105MHz (9.5ns)	HY5Y2B2A(L/S)F(P)-HE	FBGA(90ball)	4Bank, 3.0V/3.0V	3Q04	
			HY5S2B2A(L/S)F(P)-PE	FBGA(90ball)	4Bank, 1.8V/1.8V	Now	
			HY5W6B6D(L/S)F(P)-HE	FBGA(54ball)	4Bank, 2.5V/2.5V	Now	
256Mb	16M x 16	133MHz (266Mbps)	HY5Y6B6D(L/S)F(P)-HE	FBGA(54ball)	4Bank, 3.0V/3.0V	Now	
			HY5W6B6D(L/S)F(P)-PE	FBGA(54ball)	4Bank, 2.5V/2.5V	Now	
			HY5Y6B6D(L/S)F(P)-PE	FBGA(54ball)	4Bank, 3.0V/3.0V	Now	
512Mb	32M x 16	105MHz (200Mbps)	HY5S6B6D(L/S)F(P)-SE	FBGA(54ball)	4Bank, 1.8V/1.8V	Now	
			HY5MS7B6LF(P)-HE	FBGA(60ball)	4Bank, 1.8V/1.8V	1Q05	
			HY5MS7B6LF(P)-PE	FBGA(60ball)	4Bank, 1.8V/1.8V	1Q05	

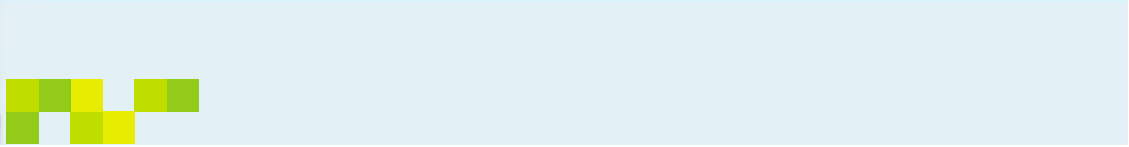
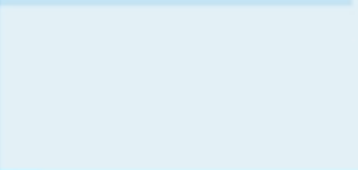
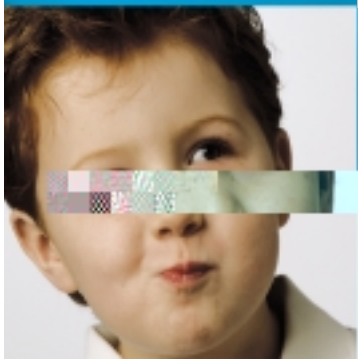
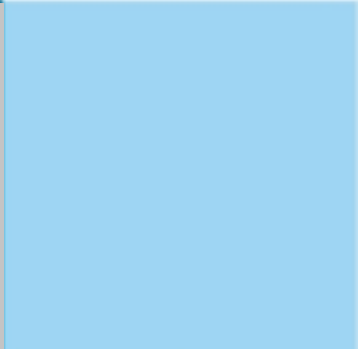
HANDY DDR SDRAM

DENSITY	ORG.	SPEED	PART NUMBER	PKG.	FEATURE	AVAIL.
512Mb	32M x 16	133MHz (266Mbps)	HY5MS7B6LF(P)-HE	FBGA(60ball)	4Bank, 1.8V/1.8V	1Q05
		105MHz (200Mbps)	HY5MS7B6LF(P)-PE	FBGA(60ball)	4Bank, 1.8V/1.8V	1Q05
256Mb	16M x 16	133MHz (266Mbps)	HY5MS5B6LF(P)-HE	FBGA(60ball)	4Bank, 1.8/1.8V	4Q04
		105MHz (200Mbps)	HY5MS5B6LF(P)-PE	FBGA(60ball)	4Bank, 1.8/1.8V	4Q04

* All SDRAM is Available For Lead Free



Opened the way to
Powerful
Future



DDR SDRAM MODULE PART NUMBERING

HYM XX X XX X XX X X X X X X X X - XX
 (1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13) (14) (15)

(1) HYNIX MODULE

(2) COMPONENT GROUP

D1 : 128Mb DDR SDRAM
 D2 : 256Mb DDR SDRAM
 D5 : 512Mb DDR SDRAM
 DG : 1Gb DDR SDRAM

(3) POWER SUPPLY & INTERFACE

BLANK : VDD 2.5V & VDDQ 2.5V
 W : VDD 2.5V & VDDQ 1.8V
 S : VDD 1.8V & VDDQ 1.8V

(4) MEMORY DEPTH

8 : 8M 25 : 256M
 16 : 16M 51 : 512M
 32 : 32M 1G : 1G
 64 : 64M 2G : 2G
 12 : 128M

(5) MODULE TYPE

BLANK : 184pin Unbuffered DIMM
 G : 184pin Registered DIMM
 M : 200pin SO DIMM
 R : 200pin Registered DIMM
 E : 208pin Registered DIMM
 U : 172pin Micro SO DIMM

(6) DATA WIDTH

64 : x64
 72 : x72

(7) REFRESH/ BANKS

1 : 4K Ref. / 2Banks 2 : 8K Ref. / 2Banks
 3 : 16k Ref. / 2Banks 5 : 4k Ref. / 4Banks
 6 : 8K Ref. / 4Banks 7 : 16K Ref. / 4Banks

(8) DIE GENERATION

BLANK : 1st Gen.
 A : 2nd Gen.
 B : 3rd Gen.
 C : 4th Gen.

(15) SPEED

D5 : DDR500 3-4-4
 D43 : DDR400 3-3-3
 D4 : DDR400 3-4-4
 J : DDR333 2.5-3-3
 M : DDR266 2-2-2
 K : DDR266A 2-3-3
 H : DDR266B 2.5-3-3
 L : DDR200 2-2-2

(14) MODULE REVISION

BLANK : Original
 A-H : Module Rev.
 M : Low Profile
 R : Low Cost
 J : DDR333/400 Unbuffered DIMM
 N: DDR400 Registered DIMM
 U: IBM System Regatta E4
 K: DDR500 Unbuffered DIMM

(13) COMPONENT CONFIGURATION

4 : x4 Based
 8 : x8 Based
 6 : x16 Based

(12) PACKAGE MATERIAL

BLANK : Normal
 P : Lead free(ROHS* Compliant)
 R : Lead & Halogen free
 (ROHS* Compliant)

(11) PACKAGE STACK

BLANK : Single Die
 S : Hynix Stack
 K : M&T Stack
 J : Other Stack
 M : Hynix DDP

(10) PACKAGE TYPE

BLANK : TSOP
 F : FBGA

(9) POWER CONSUMPTION

BLANK : Normal
 L : Low Power

♣ All DDR Modules follow above part Numbering System
 * ROHS (Restriction of Hazardous Substances)

DDR2 SDRAM MODULE PART NUMBERING

HYM XX X XX X XX X X X X X X - XX
(1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13)

(1) HYNIX MODULE

(2) COMPONENT GROUP

P2 : 256Mb DDR2 SDRAM
8K Ref./4Banks
P5 : 512Mb DDR2 SDRAM
8K Ref./4Banks
P1 : 1Gb DDR2 SDRAM
8K Ref./8Banks**
P3 : 2Gb DDR2 SDRAM
8K Ref./8Banks
P4 : 4Gb DDR2 SDRAM
8K Ref./8Banks

(3) POWER SUPPLY & INTERFACE

BLANK : VDD 1.8V & VDDQ 1.8V

(4) MEMORY DEPTH

16 : 16M 51 : 512M
32 : 32M 1G : 1G
64 : 64M 2G : 2G
12 : 128M
25 : 256M

(5) MODULE TYPE

B : Buffered DIMM
E : 276pin Registered DIMM
M : 214pin Micro-DIMM
N : 244pin Mini-DIMM
P : 240pin Registered DIMM with address parity
R : 240pin Registered DIMM
S : 200pin SO-DIMM
U : 240pin Unbuffered DIMM

(6) DATA WIDTH

64 : x64
72 : x72

(13) SPEED

S6 : DDR2-800 6-6-6
S5 : DDR2-800 5-5-5
Y6 : DDR2-667 6-6-6
Y5 : DDR2-667 5-5-5
Y4 : DDR2-667 4-4-4
C5 : DDR2-533 5-5-5
C4 : DDR2-533 4-4-4
C3 : DDR2-533 3-3-3
E4 : DDR2-400 4-4-4
E3 : DDR2-400 3-3-3

(12) MODULE REVISION

BLANK : Original
A-H : Module Rev.

(11) COMPONENT CONFIGURATION

4 : x4 Based
8 : x8 Based
6 : x16 Based

(11) PACKAGE MATERIAL

BLANK : Normal
P : Lead free(ROHS* Compliant)
R : Lead & Halogen free
(ROHS* Compliant)

(9) PACKAGE TYPE

BLANK : FBGA Single Die
S : FBGA Stack
M : FBGA DDP
(Dual Die Package)

(8) POWER CONSUMPTION

BLANK : Normal
L : Low Power

(7) DIE GENERATION

BLANK : 1st Gen.
A : 2nd Gen.
B : 3rd Gen.
C : 4th Gen.

♣ All DDR2 Modules follow above part Numbering System
* ROHS (Restriction of Hazardous Substances)
** Exception: 8K Ref./4Banks for DDP

SDRAM MODULE PART NUMBERING

HYM XX X XX X XX X XX X XX X X X - X
(1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13) (14)

(1) HYNIX MODULE

(2) COMPONENT GROUP

76 : 64Mb SDRAM
 71 : 128Mb SDRAM
 72 : 256Mb SDRAM
 75 : 512Mb SDRAM
 7G : 1Gb SDRAM

(3) POWER SUPPLY & INTERFACE

V : CMOS, 3.3V, LVTTTL
 S : SSTL_3

(4) MEMORY DEPTH

4 : 4M 16 : 16M
 8 : 8M 64 : 64M
 32 : 32M 25 : 256M
 12 : 128M

(5) MODULE TYPE

BLANK : 168pin Unbuffered DIMM
 R : JEDEC 168pin Reg. DIMM W/PLL
 E : INTEL 168pin Reg. DIMM W/O PLL
 S : INTEL 168pin Reg. DIMM W/PLL
 C : RCC 168pin Reg. DIMM W/PLL
 D : JEDEC 200pin Reg. DIMM W/PLL
 M : 144pin SO DIMM
 W : SUN 232pin Reg. DIMM W/PLL

(6) DATA WIDTH

64/72 : x64 / x72
 65/75 : x64 / x72 (PC100)
 63/73 : x64 / x72 (PC133)
 145 : x144 (PC100)
 143 : x144 (PC133)

(7) REFRESH/ BANKs

1 : 4K Ref. / 2Banks 5 : 4k Ref. / 4Banks
 2 : 8K Ref. / 2Banks 6 : 8K Ref. / 4Banks
 3 : 16k Ref. / 2Banks 7 : 16K Ref. / 4Banks

(14) SPEED

K : PC133 CL2
 H : PC133 CL3
 8 : PC125 CL3
 P : PC100 CL2
 S : PC100 CL3

(13) MODULE REVISION

BLANK : Original
 M : 1st Rev.
 N : 2nd Rev.

(12) COMPONENT CONFIGURATION

4 : x4 Based
 8 : x8 Based
 6 : x16 Based

(11) PACKAGE MATERIAL

BLANK : Normal
 P : Lead free
 H : Halogen free
 R : Lead & Halogen free

(10) PACKAGE TYPE

T : TSOP
 TU : TSOP+Micro SODIMM
 K : STACKED (B Type)
 S : STACKED (A Type)
 F : FBGA

(9) POWER CONSUMPTION

BLANK : Normal
 L : Low Power

(8) DIE GENERATION

Ichon	Cheong-ju
BLANK : 1st Gen.	H : 1st Gen.
A : 2nd Gen.	HA : 2nd Gen.
B : 3rd Gen.	HB : 3rd Gen.
C : 4th Gen.	HC : 4th Gen.

DRAM

MODULE

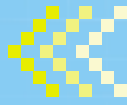
DDR SDRAM MODULE (184pin-Unbuffered)

MODULE DENSITY	BASE ORG.	COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.		
1GB	128MX72 (ECC)	64MX8	DDR400	HYMD512726A8J-D43	TSOPII(66pin)	2	1.25	Now		
				HYMD512726B8J-D43	TSOPII(66pin)	2	1.25	Now		
			DDR333	HYMD512726C8J-D43	TSOPII(66pin)	2	1.25	4Q04		
				HYMD512726A8J-J	TSOPII(66pin)	2	1.25	Now		
				HYMD512726B8J-J	TSOPII(66pin)	2	1.25	Now		
			DDR266B	HYMD512726C8J-J	TSOPII(66pin)	2	1.25	4Q04		
				HYMD512726A8-H	TSOPII(66pin)	2	1.25	Now		
	HYMD512726B8-H	TSOPII(66pin)		2	1.25	Now				
	HYMD512726C8-H	TSOPII(66pin)		2	1.25	4Q04				
	128MX64	64MX8	DDR400	HYMD512646A8J-D43	TSOPII(66pin)	2	1.25	Now		
				HYMD512646B8J-D43	TSOPII(66pin)	2	1.25	Now		
			DDR333	HYMD512646C8J-D43	TSOPII(66pin)	2	1.25	4Q04		
				HYMD512646A8J-J	TSOPII(66pin)	2	1.25	Now		
				HYMD512646B8J-J	TSOPII(66pin)	2	1.25	Now		
DDR266B			HYMD512646C8J-J	TSOPII(66pin)	2	1.25	4Q04			
			HYMD512646A8-H	TSOPII(66pin)	2	1.25	Now			
	HYMD512646B8-H	TSOPII(66pin)	2	1.25	Now					
	HYMD512646C8-H	TSOPII(66pin)	2	1.25	4Q04					
512MB	64MX72 (ECC)	64MX8	DDR400	HYMD564726A8J-D43	TSOPII(66pin)	1	1.25	Now		
				HYMD564726B8J-D43	TSOPII(66pin)	1	1.25	Now		
			DDR333	HYMD564726C8J-D43	TSOPII(66pin)	1	1.25	4Q04		
				HYMD564726A8J-J	TSOPII(66pin)	1	1.25	Now		
				HYMD564726B8J-J	TSOPII(66pin)	1	1.25	Now		
			DDR266B	HYMD564726C8J-J	TSOPII(66pin)	1	1.25	4Q04		
				HYMD564726A8-H	TSOPII(66pin)	1	1.25	Now		
				HYMD564726B8-H	TSOPII(66pin)	1	1.25	Now		
				HYMD564726C8-H	TSOPII(66pin)	1	1.25	4Q04		
			32Mx8	64MX8	DDR400	HYMD264726B8J-D43	TSOPII(66pin)	2	1.25	Now
						HYMD264726D8J-D43	TSOPII(66pin)	2	1.25	Now
					DDR333	HYMD264726B8J-J	TSOPII(66pin)	2	1.25	Now
						HYMD264726D8J-J	TSOPII(66pin)	2	1.25	Now
						HYMD264726B8-K	TSOPII(66pin)	2	1.25	Now
	DDR266A	HYMD264726D8-K			TSOPII(66pin)	2	1.25	Now		
		HYMD264726B8-H			TSOPII(66pin)	2	1.25	Now		
		HYMD264726D8-H			TSOPII(66pin)	2	1.25	Now		
		DDR266B			HYMD264726A8J-D43	TSOPII(66pin)	1	1.25	Now	
	HYMD264726B8J-D43				TSOPII(66pin)	1	1.25	Now		
	HYMD264726C8J-D43				TSOPII(66pin)	1	1.25	4Q04		
	HYMD264726A8J-J				TSOPII(66pin)	1	1.25	Now		
	HYMD264726B8J-J				TSOPII(66pin)	1	1.25	Now		
	HYMD264726C8J-J				TSOPII(66pin)	1	1.25	4Q04		
	HYMD264726A8-H		TSOPII(66pin)	1	1.25	Now				
	32Mx8	64MX8	DDR500	HYMD264646D8J-D5	TSOPII(66pin)	2	1.25	Now		
				HYMD264646B8J-D43	TSOPII(66pin)	2	1.25	Now		
			DDR400	HYMD264646D8J-D43	TSOPII(66pin)	2	1.25	Now		
				HYMD264646B8J-J	TSOPII(66pin)	2	1.25	Now		
HYMD264646D8J-J				TSOPII(66pin)	2	1.25	Now			
DDR266A			HYMD264646B8-K	TSOPII(66pin)	2	1.25	Now			
			HYMD264646D8-K	TSOPII(66pin)	2	1.25	Now			
	HYMD264646B8-H	TSOPII(66pin)	2	1.25	Now					
	HYMD264646D8-H	TSOPII(66pin)	2	1.25	Now					
256MB	32Mx72 (ECC)	32Mx8	DDR400	HYMD232726B8J-D43	TSOPII(66pin)	1	1.25	Now		

DRAM-MODULE

DRAM

MODULE



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DDR SDRAM MODULE (184pin-Unbuffered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.	
DENSITY	ORG.								
256MB	32Mx72 (ECC)	32Mx8	DDR400	HYMD232726D8J-D43	TSOPII(66pin)	1	1.25	Now	
			DDR333	HYMD232726B8J-J	TSOPII(66pin)	1	1.25	Now	
				HYMD232726D8J-J	TSOPII(66pin)	1	1.25	Now	
			DDR266A	HYMD232726B8-K	TSOPII(66pin)	1	1.25	Now	
				HYMD232726D8-K	TSOPII(66pin)	1	1.25	Now	
			DDR266B	HYMD232726B8-H	TSOPII(66pin)	1	1.25	Now	
		HYMD232726D8-H	TSOPII(66pin)	1	1.25	Now			
		32Mx64	32Mx8	DDR500	HYMD232646D8J-D5	TSOPII(66pin)	1	1.25	Now
	DDR400			HYMD232646B8J-D43	TSOPII(66pin)	1	1.25	Now	
				HYMD232646D8J-D43	TSOPII(66pin)	1	1.25	Now	
	DDR333			HYMD232646B8J-J	TSOPII(66pin)	1	1.25	Now	
				HYMD232646D8J-J	TSOPII(66pin)	1	1.25	Now	
	DDR266A			HYMD232646B8-K	TSOPII(66pin)	1	1.25	Now	
				HYMD232646D8-K	TSOPII(66pin)	1	1.25	Now	
DDR266B	HYMD232646B8-H			TSOPII(66pin)	1	1.25	Now		
	HYMD232646D8-H	TSOPII(66pin)	1	1.25	Now				
128MB	16Mx64	16Mx16	DDR400	HYMD216646B6J-D43	TSOPII(66pin)	1	1.25	Now	
				HYMD216646D6J-D43	TSOPII(66pin)	1	1.25	Now	
			DDR333	HYMD216646B6J-J	TSOPII(66pin)	1	1.25	Now	
				HYMD216646D6J-J	TSOPII(66pin)	1	1.25	Now	
			DDR266A	HYMD216646B6-K	TSOPII(66pin)	1	1.25	Now	
				HYMD216646D6-K	TSOPII(66pin)	1	1.25	Now	
	DDR266B	HYMD216646B6-H	TSOPII(66pin)	1	1.25	Now			
		HYMD216646D6-H	TSOPII(66pin)	1	1.25	Now			

DRAM-MODULE

DDR SDRAM MODULE (184pin-Registered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.	
DENSITY	ORG.								
2GB	256MX72	128MX4 (Planar Stack)	DDR400	HYMD525G726CF4N-D43	FBGA(60ball)	2	1.2	4Q04	
			DDR333	HYMD525G726CF4N-J	FBGA(60ball)	2	1.2	4Q04	
		256Mx4 (Stack)	DDR266A	HYMD525G726AS4-K	TSOPII(66pin)	2	1.7	Now	
				HYMD525G726AS4M-K	TSOPII(66pin)	2	1.2	Now	
				HYMD525G726BS4-K	TSOPII(66pin)	2	1.7	Now	
				HYMD525G726BS4M-K	TSOPII(66pin)	2	1.2	Now	
				HYMD525G726CS4-K	TSOPII(66pin)	2	1.7	4Q04	
				HYMD525G726CS4M-K	TSOPII(66pin)	2	1.2	4Q04	
				DDR266B	HYMD525G726AS4-H	TSOPII(66pin)	2	1.7	Now
					HYMD525G726AS4M-H	TSOPII(66pin)	2	1.2	Now
		HYMD525G726BS4-H	TSOPII(66pin)		2	1.7	Now		
		HYMD525G726BS4M-H	TSOPII(66pin)		2	1.2	Now		
			DDR200	HYMD525G726CS4-H	TSOPII(66pin)	2	1.7	4Q04	
		HYMD525G726CS4M-H		TSOPII(66pin)	2	1.2	4Q04		
		HYMD525G726AS4-L		TSOPII(66pin)	2	1.7	Now		
		HYMD525G726AS4M-L		TSOPII(66pin)	2	1.2	Now		
			DDR266A	HYMD525G726BS4-L	TSOPII(66pin)	2	1.7	Now	
		HYMD525G726BS4M-L		TSOPII(66pin)	2	1.2	Now		
		HYMD525G726CS4-L		TSOPII(66pin)	2	1.7	4Q04		
		HYMD525G726CS4M-L		TSOPII(66pin)	2	1.2	4Q04		

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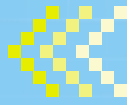
DDR SDRAM MODULE (184pin-Registered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.		
DENSITY	ORG.									
1GB	128MX72	128MX4	DDR400	HYMD512G726BF4N-D43	FBGA(60ball)	1	1.2	Now		
				HYMD512G726CF4N-D43	FBGA(60ball)	1	1.2	4Q04		
				DDR333	HYMD512G726BF4N-J	FBGA(60ball)	1	1.2	Now	
			HYMD512G726CF4N-J	FBGA(60ball)	1	1.2	4Q04			
			64Mx4 (Planar Stack)	DDR400	HYMD212G726BF4-D43	FBGA(60ball)	2	1.2	Now	
					HYMD212G726DF4-D43	FBGA(60ball)	2	1.2	Now	
		DDR333			HYMD212G726BF4-J	FBGA(60ball)	2	1.2	Now	
		HYMD212G726DF4-J	FBGA(60ball)	2	1.2	Now				
		128Mx4 (Stack)	DDR266A	HYMD212G726BS4-K	TSOPII(66pin)	2	1.7	Now		
				HYMD212G726DS4-K	TSOPII(66pin)	2	1.7	Now		
				HYMD212G726BS4M-K	TSOPII(66pin)	2	1.2	Now		
				HYMD212G726DS4M-K	TSOPII(66pin)	2	1.2	Now		
				DDR266B	HYMD212G726BS4-H	TSOPII(66pin)	2	1.7	Now	
					HYMD212G726DS4-H	TSOPII(66pin)	2	1.7	Now	
			DDR200	HYMD212G726BS4M-H	TSOPII(66pin)	2	1.2	Now		
				HYMD212G726DS4M-H	TSOPII(66pin)	2	1.2	Now		
				HYMD212G726BS4-L	TSOPII(66pin)	2	1.7	Now		
				HYMD212G726DS4-L	TSOPII(66pin)	2	1.7	Now		
512MB	64Mx72			32Mx8	DDR266A	HYMD264G726B8-K	TSOPII(66pin)	2	1.7	Now
						HYMD264G726D8-K	TSOPII(66pin)	2	1.7	Now
		HYMD264G726B8M-K	TSOPII(66pin)			2	1.2	Now		
		HYMD264G726D8M-K	TSOPII(66pin)			2	1.2	Now		
		DDR266B	HYMD264G726B8-H			TSOPII(66pin)	2	1.7	Now	
			HYMD264G726D8-H			TSOPII(66pin)	2	1.7	Now	
		HYMD264G726B8M-H	TSOPII(66pin)		2	1.2	Now			
		HYMD264G726D8M-H	TSOPII(66pin)		2	1.2	Now			
		64Mx4	DDR400		HYMD264G726BF4N-D43	FBGA(60ball)	1	1.2	Now	
					HYMD264G726DF4N-D43	FBGA(60ball)	1	1.2	4Q04	
					DDR333	HYMD264G726BF4N-J	FBGA(60ball)	1	1.2	Now
			HYMD264G726DF4N-J		FBGA(60ball)	1	1.2	4Q04		
			DDR266A	HYMD264G726B4-K	TSOPII(66pin)	1	1.7	Now		
				HYMD264G726D4-K	TSOPII(66pin)	1	1.7	Now		
		DDR266B		HYMD264G726B4M-K	TSOPII(66pin)	1	1.2	Now		
			HYMD264G726D4M-K	TSOPII(66pin)	1	1.2	Now			
			HYMD264G726B4-H	TSOPII(66pin)	1	1.7	Now			
		HYMD264G726D4-H	TSOPII(66pin)	1	1.7	Now				
HYMD264G726B4M-H	TSOPII(66pin)	1	1.2	Now						
HYMD264G726D4M-H	TSOPII(66pin)	1	1.2	Now						
64MX8	DDR400	HYMD564G726BF8N-D43	FBGA(60ball)	1	1.2	Now				
		HYMD564G726CF8N-D43	FBGA(60ball)	1	1.2	4Q04				
		DDR333	HYMD564G726BF8N-J	FBGA(60ball)	1	1.2	Now			
	HYMD564G726CF8N-J	FBGA(60ball)	1	1.2	4Q04					
	256MB	32Mx72	32Mx8	DDR400	HYMD232G726BF8N-D43	FBGA(60ball)	1	1.2	Now	
					HYMD232G726DF8N-D43	FBGA(60ball)	1	1.2	Now	
DDR333					HYMD232G726BF8N-J	FBGA(60ball)	1	1.2	Now	
HYMD232G726DF8N-J					FBGA(60ball)	1	1.2	Now		
DDR266A					HYMD232G726B8-K	TSOPII(66pin)	1	1.7	Now	
					HYMD232G726D8-K	TSOPII(66pin)	1	1.7	Now	
DDR266B				HYMD232G726B8M-K	TSOPII(66pin)	1	1.2	Now		
				HYMD232G726D8M-K	TSOPII(66pin)	1	1.2	Now		
				HYMD232G726B8-H	TSOPII(66pin)	1	1.7	Now		
				HYMD232G726D8-H	TSOPII(66pin)	1	1.7	Now		
				HYMD232G726B8M-H	TSOPII(66pin)	1	1.2	Now		
				HYMD232G726D8M-H	TSOPII(66pin)	1	1.2	Now		

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DDR SDRAM MODULE (200pin-SODIMM)

DRAM-MODULE

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.			
DENSITY	ORG.										
1GB	128MX64	64MX8 (Planar Stack)	DDR400	HYMD512M646B(L)F8-D43	FBGA(60ball)	2	1.25	Now			
				HYMD512M646C(L)F8-D43	FBGA(60ball)	2	1.25	4Q04			
			DDR333	HYMD512M646B(L)F8-J	FBGA(60ball)	2	1.25	Now			
				HYMD512M646C(L)F8-J	FBGA(60ball)	2	1.25	4Q04			
				DDR266B	HYMD512M646B(L)F8-H	FBGA(60ball)	2	1.25	Now		
					HYMD512M646C(L)F8-H	FBGA(60ball)	2	1.25	4Q04		
512MB	64MX64	32MX16	DDR400	HYMD564M646A(L)6-D43	TSOPII(66pin)	2	1.25	Now			
				HYMD564M646B(L)6-D43	TSOPII(66pin)	2	1.25	Now			
				HYMD564M646C(L)6-D43	TSOPII(66pin)	2	1.25	4Q04			
			DDR333	HYMD564M646A(L)6-J	TSOPII(66pin)	2	1.25	Now			
				HYMD564M646B(L)6-J	TSOPII(66pin)	2	1.25	Now			
				DDR266B	HYMD564M646C(L)6-J	TSOPII(66pin)	2	1.25	4Q04		
					HYMD564M646A(L)6-H	TSOPII(66pin)	2	1.25	Now		
			256MB	32Mx64	16Mx16	DDR400	HYMD232M646D(L)6-D43	TSOPII(66pin)	2	1.25	Now
							HYMD232M646D(L)6-J	TSOPII(66pin)	2	1.25	Now
						DDR266A	HYMD232M646D(L)6-K	TSOPII(66pin)	2	1.25	Now
HYMD232M646D(L)6-H	TSOPII(66pin)	2					1.25	Now			
32Mx8	DDR400	HYMD232M646B(L)8-D43				TSOPII(66pin)	1	1.25	Now		
		HYMD232M646D(L)8-D43				TSOPII(66pin)	1	1.25	Now		
	DDR333	HYMD232M646B(L)8-J				TSOPII(66pin)	1	1.25	Now		
		HYMD232M646D(L)8-J			TSOPII(66pin)	1	1.25	Now			
		DDR266A			HYMD232M646B(L)8-K	TSOPII(66pin)	1	1.25	Now		
	HYMD232M646D(L)8-K				TSOPII(66pin)	1	1.25	Now			
	DDR266B	HYMD232M646B(L)8-H			TSOPII(66pin)	1	1.25	Now			
HYMD232M646D(L)8-H		TSOPII(66pin)			1	1.25	Now				
128MB	16Mx64	16Mx16			DDR400	HYMD216M646D(L)6-D43	TSOPII(66pin)	1	1.25	Now	
						HYMD216M646D(L)6-J	TSOPII(66pin)	1	1.25	Now	
			DDR266A	HYMD216M646D(L)6-K	TSOPII(66pin)	1	1.25	Now			
				DDR266B	HYMD216M646D(L)6-H	TSOPII(66pin)	1	1.25	Now		

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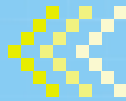
DDR2 SDRAM MODULE (240pin-Unbuffered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.	
DENSITY	ORG.								
2GB	256Mx64	128Mx8	DDR2-533 4-4-4	HYMP125U648-C4	FBGA(68ball)	2	30mm	3Q04	
			DDR2-400 3-3-3	HYMP125U648-E3	FBGA(68ball)	2	30mm	3Q04	
	256Mx72	128Mx8	DDR2-533 4-4-4	HYMP125U728-C4	FBGA(68ball)	2	30mm	3Q04	
			DDR2-400 3-3-3	HYMP125U728-E3	FBGA(68ball)	2	30mm	3Q04	
1GB	128Mx64	128Mx8	DDR2-533 4-4-4	HYMP112U648-C4	FBGA(68ball)	1	30mm	3Q04	
			DDR2-400 3-3-3	HYMP112U648-E3	FBGA(68ball)	1	30mm	3Q04	
	128Mx72	128Mx8	DDR2-533 4-4-4	HYMP112U728-C4	FBGA(68ball)	1	30mm	3Q04	
			DDR2-400 3-3-3	HYMP112U728-E3	FBGA(68ball)	1	30mm	3Q04	
	128Mx64	64Mx8	DDR2-667 5-5-5	HYMP512U648-Y5	FBGA(60ball)	2	30mm	3Q04	
			DDR2-533 4-4-4	HYMP512U648-C4	FBGA(60ball)	2	30mm	Now	
			DDR2-400 3-3-3	HYMP512U648-E3	FBGA(60ball)	2	30mm	Now	
			DDR2-667 5-5-5	HYMP512U728-Y5	FBGA(60ball)	2	30mm	3Q04	
			DDR2-533 4-4-4	HYMP512U728-C4	FBGA(60ball)	2	30mm	Now	
			DDR2-400 3-3-3	HYMP512U728-E3	FBGA(60ball)	2	30mm	Now	
	512MB	64Mx64	32Mx8	DDR2-667 5-5-5	HYMP264U648-Y5	FBGA(60ball)	2	30mm	3Q04
				DDR2-533 4-4-4	HYMP264U648-C4	FBGA(60ball)	2	30mm	Now
DDR2-400 3-3-3				HYMP264U648-E3	FBGA(60ball)	2	30mm	Now	
64Mx72		32Mx8	DDR2-667 5-5-5	HYMP264U728-Y5	FBGA(60ball)	2	30mm	3Q04	
			DDR2-533 4-4-4	HYMP264U728-C4	FBGA(60ball)	2	30mm	Now	
			DDR2-400 3-3-3	HYMP264U728-E3	FBGA(60ball)	2	30mm	Now	
64Mx64		64Mx8	DDR2-667 5-5-5	HYMP564U648-Y5	FBGA(60ball)	1	30mm	3Q04	
			DDR2-533 4-4-4	HYMP564U648-C4	FBGA(60ball)	1	30mm	Now	
			DDR2-400 3-3-3	HYMP564U648-E3	FBGA(60ball)	1	30mm	Now	
64Mx72		64Mx8	DDR2-667 5-5-5	HYMP564U728-Y5	FBGA(60ball)	1	30mm	3Q04	
			DDR2-533 4-4-4	HYMP564U728-C4	FBGA(60ball)	1	30mm	Now	
			DDR2-400 3-3-3	HYMP564U728-E3	FBGA(60ball)	1	30mm	Now	
256MB	32Mx64	32Mx8	DDR2-667 5-5-5	HYMP232U648-Y5	FBGA(60ball)	1	30mm	3Q04	
			DDR2-533 4-4-4	HYMP232U648-C4	FBGA(60ball)	1	30mm	Now	
			DDR2-400 3-3-3	HYMP232U648-E3	FBGA(60ball)	1	30mm	Now	
	32Mx72	32Mx8	DDR2-667 5-5-5	HYMP232U728-Y5	FBGA(60ball)	1	30mm	3Q04	
			DDR2-533 4-4-4	HYMP232U728-C4	FBGA(60ball)	1	30mm	Now	
			DDR2-400 3-3-3	HYMP232U728-E3	FBGA(60ball)	1	30mm	Now	
	32Mx64	32Mx16	DDR2-667 5-5-5	HYMP532U646-Y5	FBGA(84ball)	1	30mm	3Q04	
			DDR2-533 4-4-4	HYMP532U646-C4	FBGA(84ball)	1	30mm	Now	
			DDR2-400 3-3-3	HYMP532U646-E3	FBGA(84ball)	1	30mm	Now	
	32Mx72	32Mx16	DDR2-667 5-5-5	HYMP532U726-Y5	FBGA(84ball)	1	30mm	3Q04	
			DDR2-533 4-4-4	HYMP532U726-C4	FBGA(84ball)	1	30mm	Now	
			DDR2-400 3-3-3	HYMP532U726-E3	FBGA(84ball)	1	30mm	Now	
128MB	16Mx64	16Mx16	DDR2-667 5-5-5	HYMP216U646-Y5	FBGA(84ball)	1	30mm	3Q04	
			DDR2-533 4-4-4	HYMP216U646-C4	FBGA(84ball)	1	30mm	Now	
			DDR2-400 3-3-3	HYMP216U646-E3	FBGA(84ball)	1	30mm	Now	

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DDR2 SDRAM MODULE (240pin-Registered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.
DENSITY	ORG.							
4GB	512Mx72	512Mx4 (Stack)	DDR2-533 4-4-4	HYMP351R72M4-C4	FBGA(71ball)	2	30mm	3Q04
			DDR2-400 3-3-3	HYMP351R72M4-E3	FBGA(71ball)	2	30mm	3Q04
2GB	256Mx72	256Mx4	DDR2-533 4-4-4	HYMP125R724-C4	FBGA(68ball)	1	30mm	3Q04
			DDR2-400 3-3-3	HYMP125R724-E3	FBGA(68ball)	1	30mm	3Q04
		256Mx4 (Stack)	DDR2-533 4-4-4	HYMP125R72M4-C4	FBGA(63ball)	2	30mm	Now
			DDR2-400 3-3-3	HYMP125R72M4-E3	FBGA(63ball)	2	30mm	Now
		128Mx8	DDR2-533 4-4-4	HYMP125R728-C4	FBGA(68ball)	2	30mm	3Q04
			DDR2-400 3-3-3	HYMP125R728-E3	FBGA(68ball)	2	30mm	3Q04
1GB	128Mx72	128Mx4	DDR2-533 4-4-4	HYMP512R724-C4	FBGA(60ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP512R724-E3	FBGA(60ball)	1	30mm	Now
		128Mx8	DDR2-533 4-4-4	HYMP112R728-C4	FBGA(68ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP112R728-E3	FBGA(68ball)	1	30mm	Now
		64Mx8	DDR2-533 4-4-4	HYMP512R728-C4	FBGA(60ball)	2	30mm	Now
			DDR2-400 3-3-3	HYMP512R728-E3	FBGA(60ball)	2	30mm	Now
512MB	64Mx72	64Mx4	DDR2-533 4-4-4	HYMP264R724-C4	FBGA(60ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP264R724-E3	FBGA(60ball)	1	30mm	Now
		64Mx8	DDR2-533 4-4-4	HYMP564R728-C4	FBGA(60ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP564R728-E3	FBGA(60ball)	1	30mm	Now
		32Mx8	DDR2-533 4-4-4	HYMP264R728-C4	FBGA(60ball)	2	30mm	Now
			DDR2-400 3-3-3	HYMP264R728-E3	FBGA(60ball)	2	30mm	Now
256MB	32Mx72	32Mx8	DDR2-533 4-4-4	HYMP232R728-C4	FBGA(60ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP232R728-E3	FBGA(60ball)	1	30mm	Now

DDR2 SDRAM MODULE (200pin-SODIMM)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.
DENSITY	ORG.							
2GB	256Mx64	256Mx8 (Stack)	DDR2-533 4-4-4	HYMP325S64M8-C4	FBGA(71ball)	2	30mm	3Q04
			DDR2-400 3-3-3	HYMP325S64M8-E3	FBGA(71ball)	2	30mm	3Q04
1GB	128Mx64	128Mx8	DDR2-533 4-4-4	HYMP112S648-C4	FBGA(68ball)	1	30mm	3Q04
			DDR2-400 3-3-3	HYMP112S648-E3	FBGA(68ball)	1	30mm	3Q04
		128Mx8 (Stack)	DDR2-533 4-4-4	HYMP112S64M8-C4	FBGA(63ball)	2	30mm	3Q04
			DDR2-400 3-3-3	HYMP112S64M8-E3	FBGA(63ball)	2	30mm	3Q04
512MB	64Mx64	64Mx8	DDR2-533 4-4-4	HYMP564S648-C4	FBGA(60ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP564S648-E3	FBGA(60ball)	1	30mm	Now
		32Mx16	DDR2-533 4-4-4	HYMP564S646-C4	FBGA(84ball)	2	30mm	Now
			DDR2-400 3-3-3	HYMP564S646-E3	FBGA(84ball)	2	30mm	Now
			DDR2-400 3-3-3	HYMP564S64A6-C4	FBGA(84ball)	2	30mm	3Q04
				HYMP564S64A6-E3	FBGA(84ball)	2	30mm	Now
256MB	32Mx64	32Mx8	DDR2-533 4-4-4	HYMP232S648-C4	FBGA(60ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP232S648-E3	FBGA(60ball)	1	30mm	Now
		32Mx16	DDR2-533 4-4-4	HYMP532S646-C4	FBGA(84ball)	1	30mm	Now
			DDR2-400 3-3-3	HYMP532S646-E3	FBGA(84ball)	1	30mm	3Q04
		DDR2-400 3-3-3	HYMP532S64E3	FBGA(84ball)	1	30mm	Now	
			HYMP532S64A6-E3	FBGA(84ball)	1	30mm	3Q04	
128MB	16Mx64	16Mx16	DDR2-533 4-4-4	HYMP232S646-C4	FBGA(84ball)	2	30mm	Now
			DDR2-400 3-3-3	HYMP232S646-E3	FBGA(84ball)	2	30mm	Now
		DDR2-533 4-4-4	HYMP216S646-C4	FBGA(84ball)	1	30mm	Now	
			HYMP216S646-E3	FBGA(84ball)	1	30mm	Now	

DRAM MODULE

SDRAM MODULE (168pin-Unbuffered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.	
DENSITY	ORG.								
512MB	64Mx72 (ECC)	32Mx8	PC133	HYM72V64736BT8-H	TSOPII(54pin)	2	1.25	EOL	
			PC100	HYM72V64756BT8-P	TSOPII(54pin)	2	1.25	EOL	
				HYM72V64756BT8-S	TSOPII(54pin)	2	1.25	EOL	
	64Mx64	32Mx8	PC133	HYM72V64636BT8-H	TSOPII(54pin)	2	1.25	EOL	
			PC100	HYM72V64656BT8-P	TSOPII(54pin)	2	1.25	EOL	
				HYM72V64656BT8-S	TSOPII(54pin)	2	1.25	EOL	
256MB	32Mx72 (ECC)	32Mx8	PC133	HYM72V32736BT8-H	TSOPII(54pin)	1	1.25	EOL	
			PC100	HYM72V32756BT8-P	TSOPII(54pin)	1	1.25	EOL	
				HYM72V32756BT8-S	TSOPII(54pin)	1	1.25	EOL	
		16Mx8	PC133	HYM71V32735HCT8-K	TSOPII(54pin)	2	1.25	EOL	
				HYM71V32735HCT8-H	TSOPII(54pin)	2	1.25	EOL	
			PC100	HYM71V32755HCT8-P	TSOPII(54pin)	2	1.25	EOL	
	32Mx64	32Mx8	PC133	HYM72V32636BT8-H	TSOPII(54pin)	1	1.25	EOL	
			PC100	HYM72V32656BT8-P	TSOPII(54pin)	1	1.25	EOL	
				HYM72V32656BT8-S	TSOPII(54pin)	1	1.25	EOL	
	16Mx8	32Mx8	PC133	HYM71V32635HCT8-K	TSOPII(54pin)	2	1.25	EOL	
				HYM71V32635HCT8-H	TSOPII(54pin)	2	1.25	EOL	
			PC100	HYM71V32655HCT8-P	TSOPII(54pin)	2	1.25	EOL	
	128MB	16Mx72 (ECC)	16Mx8	PC133	HYM71V16735HCT8-K	TSOPII(54pin)	1	1.25	EOL
					HYM71V16735HCT8-H	TSOPII(54pin)	1	1.25	EOL
				PC100	HYM71V16755HCT8-P	TSOPII(54pin)	1	1.25	EOL
16Mx64	16Mx8	16Mx8	PC133	HYM71V16635HCT8-K	TSOPII(54pin)	1	1.25	EOL	
				HYM71V16635HCT8-H	TSOPII(54pin)	1	1.25	EOL	
			PC100	HYM71V16655HCT8-P	TSOPII(54pin)	1	1.25	EOL	
16Mx16	16Mx8	16Mx16	PC133	HYM72V16635BT6-H	TSOPII(54pin)	1	1.25	EOL	
			PC100	HYM72V16655BT6-P	TSOPII(54pin)	1	1.25	EOL	
				HYM72V16655BT6-S	TSOPII(54pin)	1	1.25	EOL	

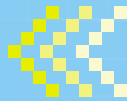
* All SDRAM Module is available for Lead Free and IT-part

SDRAM MODULE (168pin-Registered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.
DENSITY	ORG.							
1GB	128Mx72	64Mx4 (Stack)	PC133	HYM72V12C736BS4-H	TSOPII(54pin)	1	1.7	EOL
			PC100	HYM72V12C756BS4-P	TSOPII(54pin)	1	1.7	EOL
				HYM72V12C756BS4-S	TSOPII(54pin)	1	1.7	EOL
512MB	64Mx72	64Mx4	PC133	HYM72V64C736BT4-H	TSOPII(54pin)	1	1.7	EOL
			PC100	HYM72V64C756BT4-S	TSOPII(54pin)	1	1.7	EOL
256MB	32Mx72	32Mx4	PC133	HYM71V32C735HCT4-K	TSOPII(54pin)	1	1.7	EOL
				HYM71V32C735HCT4-H	TSOPII(54pin)	1	1.7	EOL

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MODULE



SDRAM MODULE (168pin-Registered)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.
DENSITY	ORG.							
256MB	32Mx72	32Mx4	PC100	HYM71V32C755HCT4-P	TSOPII(54pin)	1	1.7	EOL
				HYM71V32S755HCT4-P	TSOPII(54pin)	1	1.7	EOL
				HYM71V32D755HCT4-P	TSOPII(54pin)	1	1.7	EOL
				HYM71V32C755HCT4-S	TSOPII(54pin)	1	1.7	EOL
				HYM71V32S755HCT4-S	TSOPII(54pin)	1	1.7	EOL
				HYM71V32D755HCT4-S	TSOPII(54pin)	1	1.7	EOL
128MB	16Mx72	16Mx8	PC133	HYM71V16C735HCT8-K	TSOPII(54pin)	1	1.125	EOL
				HYM71V16C735HCT8-H	TSOPII(54pin)	1	1.125	EOL
			PC100	HYM71V16C755HCT8-P	TSOPII(54pin)	1	1.125	EOL
				HYM71V16C755HCT8-S	TSOPII(54pin)	1	1.125	EOL

* All SDRAM Module is available for Lead Free and IT-part

SDRAM MODULE (144pin-SODIMM)

MODULE		BASE COMPONENT	SPEED	PART NUMBER	COMPONENT PKG.	#OF BANK	HEIGHT	AVAIL.
DENSITY	ORG.							
256MB	32Mx64	16Mx16	PC133	HYM72V32M636BT6-H	TSOPII(54pin)	2	1.25	EOL
				HYM72V32M636C(L)T6-H	TSOPII(54pin)	2	1.25	Now
			PC100	HYM72V32M656BT6-P	TSOPII(54pin)	2	1.25	EOL
				HYM72V32M656C(L)T6-P	TSOPII(54pin)	2	1.25	Now
				HYM72V32M656BT6-S	TSOPII(54pin)	2	1.25	EOL
				HYM72V32M656C(L)T6-S	TSOPII(54pin)	2	1.25	Now
128MB	16Mx64	8Mx16	PC133	HYM71V16M635HC(L)T6-H	TSOPII(54pin)	2	1.25	Now
				HYM71V16M655HC(L)T6-P	TSOPII(54pin)	2	1.25	Now
			HYM71V16M655HC(L)T6-S	TSOPII(54pin)	2	1.25	Now	
		PC100	16Mx16	HYM72V16M635B(L)T6-H	TSOPII(54pin)	1	1.25	EOL
				HYM72V16M655B(L)T6-P	TSOPII(54pin)	1	1.25	EOL
				HYM72V16M655B(L)T6-S	TSOPII(54pin)	1	1.25	EOL

* All SDRAM Module is available for Lead Free and IT-part

DRAM-MODULE